

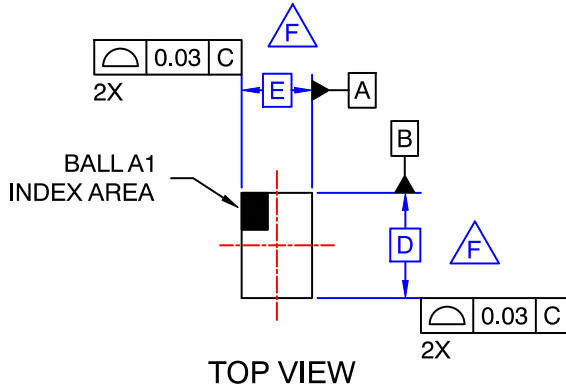
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®

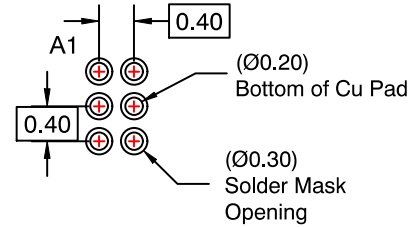


WLCSP6 1.37x0.97x0.586
CASE 567RR
ISSUE O

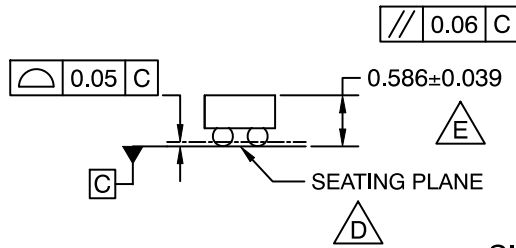
DATE 30 NOV 2016



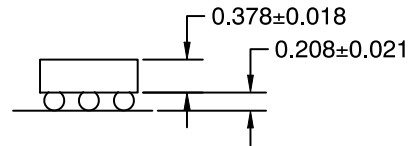
TOP VIEW



RECOMMENDED LAND PATTERN
(NSMD PAD TYPE)

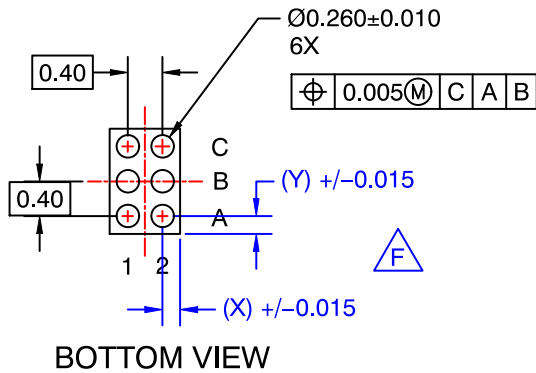


SIDE VIEWS



NOTES:

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASMEY14.5M, 2009.
- D. DATUM C, THE SEATING PLANE IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
- E. PACKAGE TYPICAL HEIGHT IS 586 MICRONS ±39 MICRONS (547–625 MICRONS).
- F. FOR DIMENSIONS D, E, X, AND Y, SEE PRODUCT DATASHEET.



BOTTOM VIEW

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	WLCSP6 1.37x0.97x0.586	PAGE 1 OF 2

